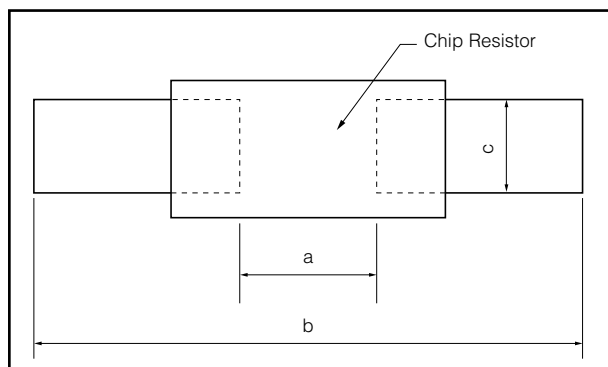


Recommended Land Pattern

- An example of a land pattern for the Rectangular Type is shown below.



High power (double-sided resistive elements structure) type

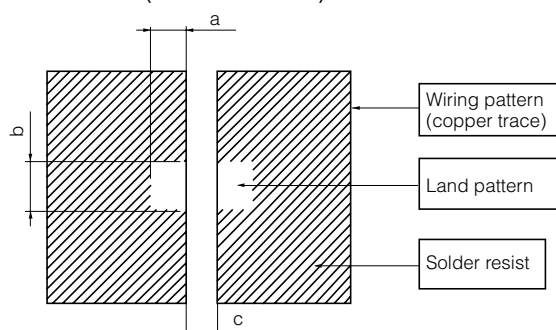
Type	Size mm/inch	Dimensions (mm)		
		a	b	c
ERJ2BW	1005/0402	0.52	1.4 to 1.6	0.4 to 0.6
ERJ3BW	1608/0603	0.5 to 0.8	2.5 to 2.7	0.9 to 1.1
ERJ6BW	2012/0805	0.9	3.2 to 3.8	1.1 to 1.4
ERJ8BW				
ERJ8CW (10 to 16 mΩ)	3216/1206	1.2	4.4 to 5.0	1.3 to 1.8
ERJ8CW (18 to 50 mΩ)	3216/1206	2.0 to 2.6	4.4 to 5.0	1.2 to 1.8

Size mm/inch	Dimensions (mm)		
	a	b	c
0402/01005	0.15 to 0.20	0.5 to 0.7	0.20 to 0.25
0603/0201	0.3 to 0.4	0.8 to 0.9	0.25 to 0.35
1005/0402	0.5 to 0.6	1.4 to 1.6	0.4 to 0.6
1608/0603	0.7 to 0.9	2.0 to 2.2	0.8 to 1.0
2012/0805	1.0 to 1.4	3.2 to 3.8	0.9 to 1.4
3216/1206	2.0 to 2.4	4.4 to 5.0	1.2 to 1.8
3225/1210	2.0 to 2.4	4.4 to 5.0	1.8 to 2.8
4532/1812	3.3 to 3.7	5.7 to 6.5	2.3 to 3.5
5025/2010	3.6 to 4.0	6.2 to 7.0	1.8 to 2.8
6432/2512	5.0 to 5.4	7.6 to 8.6	2.3 to 3.5
6432/2512*	3.6 to 4.0	7.6 to 8.6	2.3 to 3.5

* ERJL1W

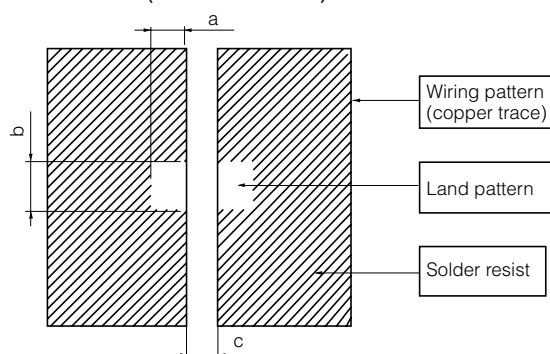
- An example of a land pattern for Low Resistance Value Chip Resistors is shown below.

ERJM03 (Size 1608/0603)



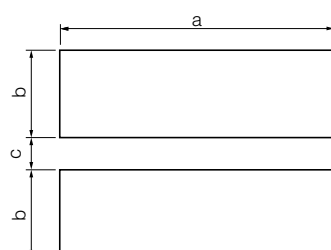
Type	Dimensions (mm)		
	a	b	c
ERJM03N	0.65	0.8	0.7

ERJM1W (Size 6432/2512)



Type	Dimensions (mm)		
	a	b	c
ERJM1WS	2.1	3.4	4.2
ERJM1WT	3.1	3.4	2.2

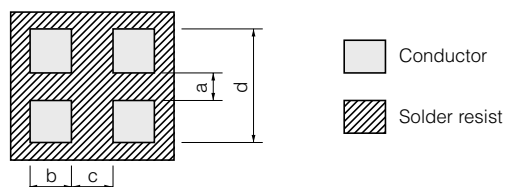
- An example of a land pattern for High Power Chip Resistors / Wide Terminal Type is shown below.



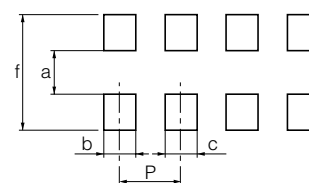
Type	Dimensions (mm)		
	a	b	c
ERJA1	6.4	1.70	0.60
ERJB1 ERJC1 ⁽¹⁾	5.0	1.30	0.75
ERJB2	3.2	0.95	0.70
ERJB3	2.0	0.80	0.60

(1) Anti-Sulfurated High Power Chip Resistors / Wide Terminal Type

- An example of a land pattern for Chip Resistor Array, Metal Film Chip Resistor Array, Anti-Sulfurated Chip Resistor Array and Chip Attenuator is shown below.

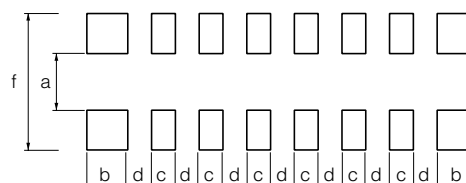
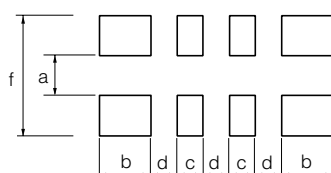


Conductor
Solder resist



Type	Dimensions (mm)			
	a	b	c	d
EXB14V EXB14A	0.30	0.30	0.30	0.80 to 0.90
EXB24V EXBU24 EXB24A	0.5	0.35 to 0.40	0.30	1.4 to 1.5

Type	Dimensions (mm)				
	a	b	c	f	P
EXB18V	0.20 to 0.30	0.15 to 0.20	0.15 to 0.20	0.80 to 0.90	0.40
EXBV4V,V8V	0.7 to 0.9	0.4 to 0.45	0.4 to 0.45	2 to 2.4	0.80
EXB34V,38V EXBU34,U38 ERA38V	0.7 to 0.9	0.4 to 0.5	0.4 to 0.5	2.2 to 2.6	0.80
EXBS8V	1 to 1.2	0.5 to 0.75	0.5 to 0.75	3.2 to 3.8	1.27



Type	Dimensions (mm)				
	a	b	c	d	f
EXB28V EXBU28	0.40	0.525	0.25	0.25	1.40
EXBN8V	0.45 to 0.50	0.35 to 0.38	0.25	0.25	1.40 to 2.00

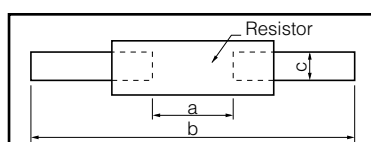
Type	Dimensions (mm)				
	a	b	c	d	f
EXB2HV EXBU2H	1.00	0.425	0.25	0.25	2.00

- An example of a land pattern for Chip Resistor Networks is shown below.

	EXBA	EXBE
For popular pattern	Pitch 1.27 mm 	Pitch 0.8 mm
For high density pattern*	Pitch 0.635 mm Through-hole less 	Pitch 0.4 mm Through-hole less
	EXBD	EXBQ
For popular pattern	Pitch 0.635 mm 	Pitch 0.5 mm

- * When designing high density land patterns, examine the reliability of isolation among the lines and adopt the chip resistor networks.

- An example of a land pattern for Fixed Metal (Oxide) Film Resistors (SMD) is shown below.



Type	Dimensions (mm)		
	a	b	c
ERG(X)1H	3.5 to 4.0	14.5 to 15.0	2.8 to 3.3
ERG(X)2H	4.0 to 4.5	17.0 to 17.5	3.1 to 3.6